

SUB C1 edge surface of the resin, the edge surfaces of the substrate and the resin are level with each other, a pair of the side surfaces make a corner portion, and the substrate is indented at the corner portion further inward than a portion of the resin.

21 cont 16. (Amended) The semiconductor device as defined in claim 15, wherein the substrate at the corner portion forms a shape that is indented in the opposite direction from the direction in which the corner portion protrudes, and thus an indented surface of the substrate is positioned further inward than the portion of the resin.

SUB B1 17. (Amended) The semiconductor device as defined in claim 15, wherein the substrate has a thinner portion at the corner portion, and a surface of the thinner portion of the substrate is indented further inward than the portion of the resin.

SUB C1 18. (Amended) The semiconductor device as defined in claim 15, wherein an indented surface of the substrate is covered by the resin.

19. (Amended) The semiconductor device as defined in claim 15, wherein a cover is provided at the corner portion, between the substrate and the resin; and wherein an indented surface of the substrate is exposed.

REMARKS

Claims 15-21 are pending. By this Amendment, claims 1-14 and 22-28 are cancelled, and claims 15-19 are amended.

Reconsideration based on the following remarks is respectfully requested.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

I. The Information Disclosure Statement Mentioned in the Office Action

The Office Action asserts that an Information Disclosure Statement was filed on July 26, 2001. No such Information Disclosure Statement has been filed in the present application. Withdrawal of this assertion is respectfully requested.